

REED SMITH LLP
A limited liability partnership formed in the State of Delaware

1 John P. Bovich (SBN 150688)
Email: jbovich@reedsmith.com
2 James A. Daire (SBN 239637)
Email: jdaire@reedsmith.com
3 REED SMITH LLP
101 Second Street, Suite 1800
4 San Francisco, CA 94105-3659
Telephone: +1 415 543 8700
5 Facsimile: +1 415 391 8269

6 Attorneys for NON-PARTY
Siemens AG

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8 UNITED STATES DISTRICT COURT
9 NORTHERN DISTRICT OF CALIFORNIA
10 San Jose Division

11 APPLE INC., a California corporation,

12 Plaintiff,

13 vs.

14 SAMSUNG ELECTRONICS CO., LTD., a
Korean corporation; SAMSUNG
15 ELECTRONICS AMERICA, INC., a New York
corporation; and SAMSUNG
16 TELECOMMUNICATIONS AMERICA, LLC, a
Delaware limited liability company,

17 Defendants.
18

No.: 11-cv-01846-LHK (PSG)

**DECLARATION OF JOHN P. BOVICH IN
SUPPORT OF NON-PARTY SIEMENS
AG'S ADMINISTRATIVE MOTION TO
SEAL**

Honorable Lucy H. Koh

19
20 I, John P. Bovich, declare and state as follows:

21 1. I am an attorney with Reed Smith LLP, counsel for non-party Siemens AG
22 (“Siemens”). I have personal knowledge of the facts stated in this Declaration and, if called as a
23 witness, could and would competently testify to them.

24 2. On July 21, 2012, Siemens received the letter attached hereto as Exhibit A from trial
25 counsel for Samsung Electronic Co. LTD. (“Samsung”), concerning Trial Exhibit 77: the Siemens
26 Patent License Agreement (“the Agreement”) and the summary of same (enclosures omitted).
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